Final Product Change Notification

201402009F01

Issue Date: 16-Mar-2014
Effective Date: 14-Jun-2014

.

Here’s your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to [view this notification online]

Management Summary

Due to the discontinuation of the 5" production line in ASMC we will move diffusion of TDA7052A/G2 die to the 6" production line in ASMC

Change Category

[X] Wafer Fab process
[ ] Wafer Fab materials
[ ] Wafer Fab location
[ ] Assembly Process
[X] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Electrical spec./Test coverage
[ ] Test Location
[ ] Design
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling

TDA7052A/G2 diffusion transfer from 5" line to 6" line

Details of this Change

Diffusion of TDA7052A/G2 die will move from 5" line to 6" line in ASMC

For TDA7052AT/N2 we will move to a new subpackage. The current subpackage uses the 71-1 adhesive, which is not APB standard adhesive. APB propose to change to subpackage which uses 84-1 adhesive instead

Why do we Implement this Change

due to discontinuation of the 5 inch line in ASMC we move diffusion of TDA7052A/G2 die to the 6 inch line.

For the SO8 package, for TDA7052AT/N2, we move to a new subpackage using APB standard adhesive 84-1

Identification of Affected Products

Top side marking

See Self Qualification Report page 6/7.

Product Availability

Sample Information

Samples are available from 24-Mar-2014

Production

Planned first shipment 02-Jun-2014

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted
For TDA7052AT/N2 we will start shipping the parts from the 6" line from early June onwards.
For TDA7056AT/N2 we will start shipping the parts from the 6" line from wk1437 onwards, and after depletion of existing inventory.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 15-Apr-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Karla Swierenga
Position	BL Quality Manager
e-mail address	Karla.Swierenga@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of $4.36 billion in 2012.

View Notification | Subscription | Support

NXP | Privacy Policy | Terms of Use

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands